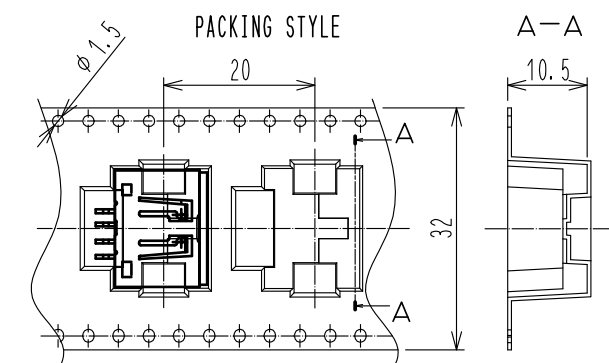
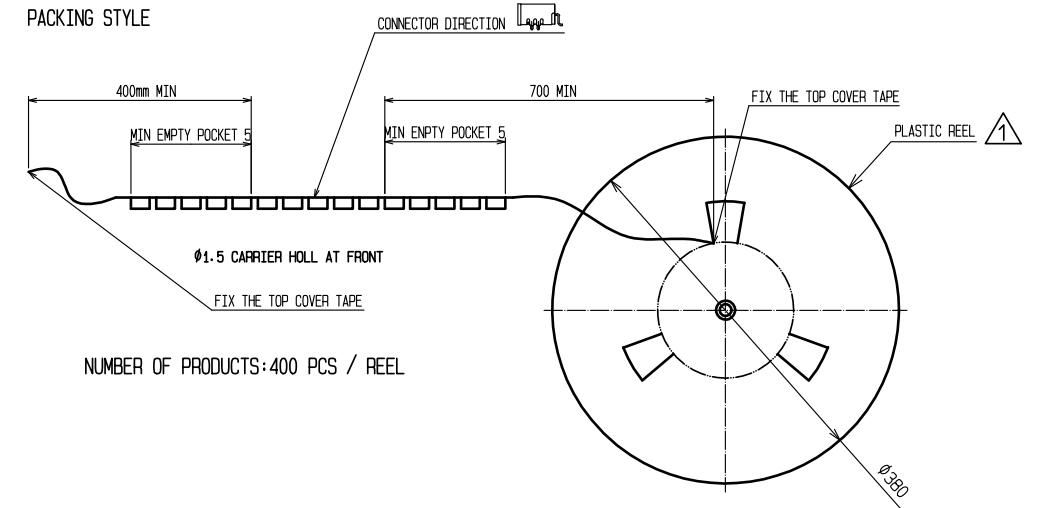
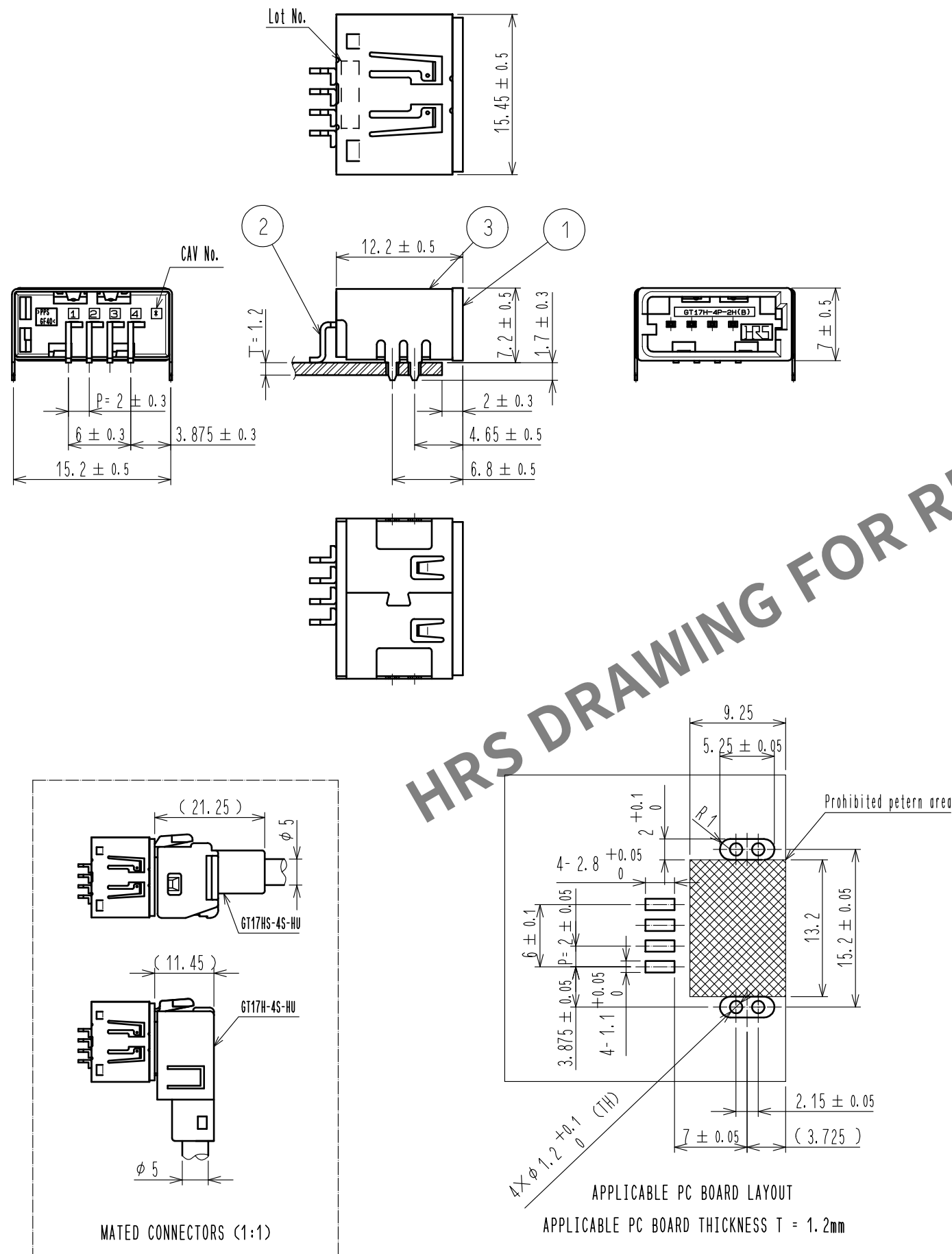
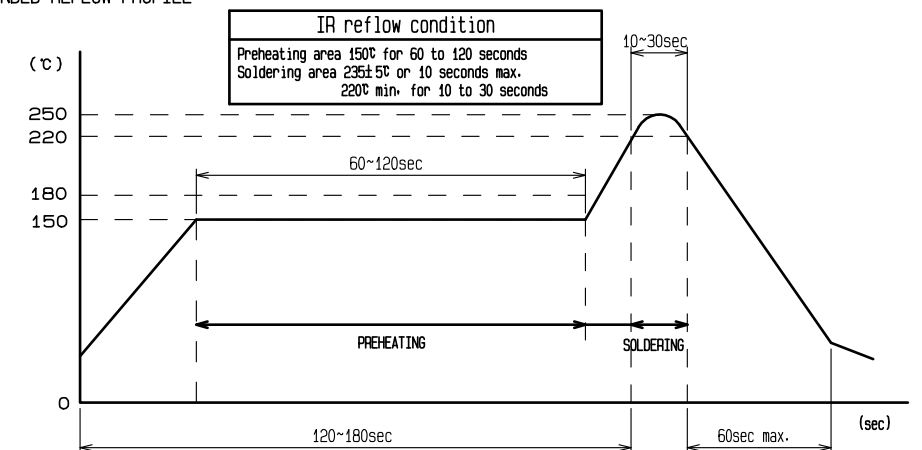


RoHS, ELV COMPLIANT

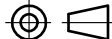


RECOMMENDED REFLOW PROFILE



Note1. The soldering process is allowed up to twice under the same condition. However, the interval between the first and second process must be maintained at the room temperature.

Note2. The temperature indicates the board surface temperature on the connector lead area.

2	BRASS	TIN PLATING						
1	PPS	GREEN			3	COPPER ALLOY	TIN PLATING	
NO.	MATERIAL	FINISH , REMARKS			NO.	MATERIAL	FINISH , REMARKS	
UNITS mm		SCALE 2 : 1		COUNT 1	DESCRIPTION OF REVISIONS DIS-T-00006678	DESIGNED TS. KUBOTA	CHECKED EJ. WAKATSUKI	DATE 20200909
 HIROSE ELECTRIC CO., LTD.		APPROVED : KI. HIROKAWA			20200326	DRAWING NO. EDC-166943-56-00		
		CHECKED : EJ. WAKATSUKI			20200325	PART NO. GT17H-4P-2H(B)(56)		
		DESIGNED : TS. KUBOTA			20200325	CODE NO. CL767-0171-9-56		
		DRAWN : YK. MITSUISHI			20200219	 		